

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS7A0312PDBVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A0312PDBVR	SN	Level-1-260C-UNLIM	Ext-Mfg	DBV 5	2.9x1.6x1.45	19

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.015753	97.385015	973850	0.083029	830
Precious Metals	Gold	7440-57-5	0.000035	0.21637	2164	0.000184	2
Precious Metals	Palladium	7440-05-3	0.000388	2.398615	23986	0.002045	20
Sub-Total			0.016176	100	1000000	0.085258	853
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.069717	80.000229	800002	0.367454	3675
Thermoplastics	Epoxy	85954-11-6	0.017429	19.999771	199998	0.091862	919
Sub-Total			0.087146	100	1000000	0.459317	4593
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	6.632428	97.535706	975357	34.957256	349573
Copper and Its Alloys	Iron	7439-89-6	0.153136	2.252	22520	0.807127	8071
Copper and Its Alloys	Phosphorus	7723-14-0	0.001496	0.022	220	0.007885	79
Precious Metals	Silver	7440-22-4	0.004304	0.063294	633	0.022685	227
Zinc and Its Alloys	Zinc	7440-66-6	0.008636	0.127	1270	0.045517	455
Sub-Total			6.8	100	1000000	35.840471	358405
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.04	100	1000000	0.210826	2108
Sub-Total			0.04	100	1000000	0.210826	2108
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.283509	86.85	868500	54.200854	542009
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.059203	0.500003	5000	0.312039	3120
Other Plastics and Rubber	Carbon Black	1333-86-4	0.017761	0.150002	1500	0.093612	936
Thermoplastics	Epoxy	85954-11-6	1.480067	12.499996	125000	7.800926	78009
Sub-Total			11.84054	100	1000000	62.407431	624074
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.189103	100	1000000	0.996697	9967
Sub-Total			0.189103	100	1000000	0.996697	9967
Total			18.972965			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.